



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: 1752

Application Number: 10/629,806

Examiner: Sin J. Lee

Filed: July 30, 2003

Confirmation No.: 9494

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR  
FORMING RESIST PATTERN, AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: 030923

Customer Number: 38834

**AMENDMENT AFTER FINAL**

**MAILSTOP: AF**

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

April 11, 2006

Sir:

In response to the Office Action dated December 13, 2005, the response due date extended to April 13, 2006 by a 1-month Extension of Time, please amend the above-identified application as follows:

**Amendments to the Claims** begin at page 2 of this paper.

**Remarks** begin on page 8 of this paper.

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S.J.L.

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